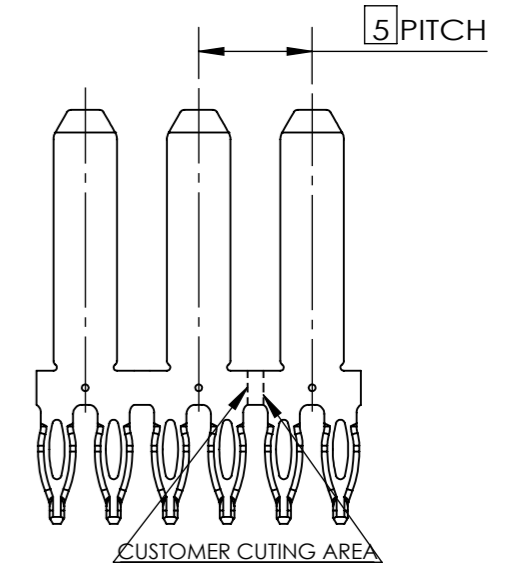
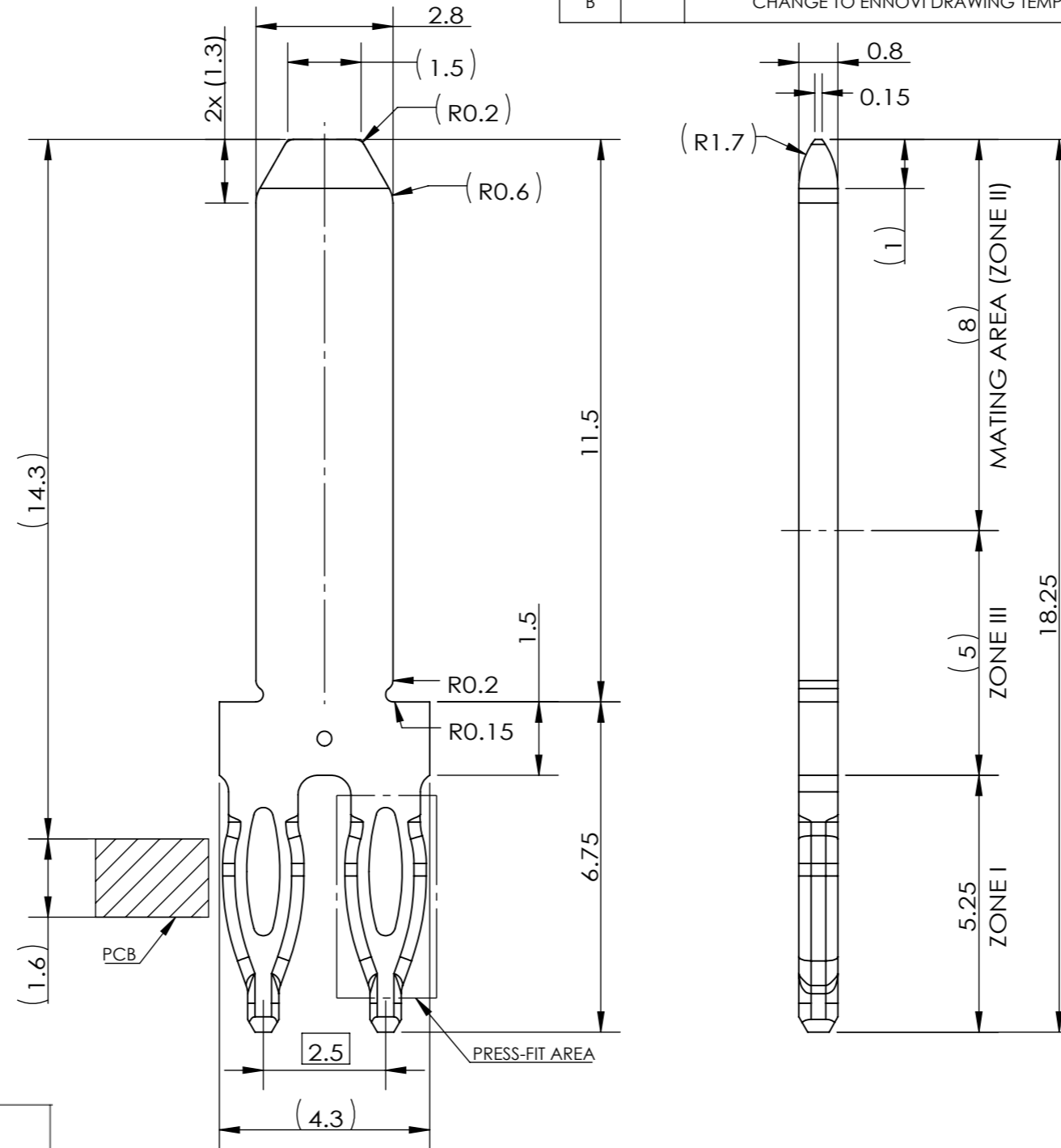


NOTES (UNLESS OTHERWISE INDICATED):

- MATERIAL: C19010, CuNiSi R580;
- OPERATION TEMPERATURE: -40~+150C
- PRESS-FIT AREA: ENNOVI STANDARD 0.8EON
- FINISH SPECIFICATION
 ZONE I (PRESS-FIT AREA): INDICOAT, REFER TO BELOW PLATING TABLE
 ZONE II: 1.0~3.0um MATTE Tin, 1.0~2.2um Ni; OR CUSTOMERIZED
 ZONE III: TRANSITION AREA, Ni PLATING, Sn ALLOWED
- ALL DIMENSIONS AFTER PLATING
- PCB FINISH: RECOMMENDED ImmSn, OPTIONAL ImAg/OSP
 PCB HOLE CONSTRUCTION: SEE BELOW CHART
- PRESS FIT DIMENSION REFER TO DRAWING E-MLG03034-APP;
 PRESS FIT PLATING REFER TO DRAWING E-MLG03034-FIN.

REV.	ZONE	DESCRIPTION	DRAWN BY DD/MM/YYYY	CHECKED BY DD/MM/YYYY	APPROVED BY DD/MM/YYYY	CHANGE NO
A	-	INITIAL RELEASE	Yin LIU 2023-12-05	-	Sohrab.MORADI 2023-12-05	-
B		CHANGE TO ENNOVI DRAWING TEMPLATE	Yin LIU 2024-07-02		Sohrab.MORADI 2027-07-02	

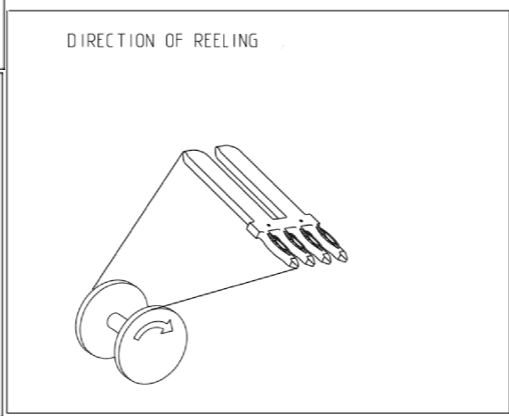
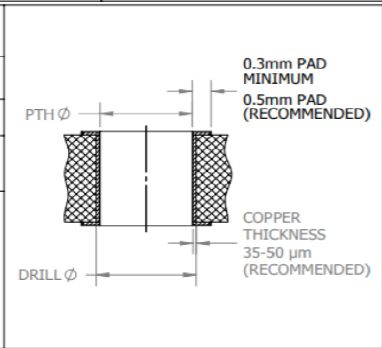


PART NUMBER	ZONE I PRESS-FIT AREA "TOP PLATE"	ZONE I PRESS-FIT AREA "UNDERPLATE"
E-MLG03034-FIN-4 (INDICOAT)	0.3 - 1.1 μm [12 - 45 μin] <ul style="list-style-type: none"> INDIUM POST-PLATED ELECTRODEPOSITED WHISKER-MITIGATED 	1.0 - 3.0 μm [39 - 120 μin] <ul style="list-style-type: none"> SULFAMATE NICKEL POST-PLATED ELECTRODEPOSITED

REQUIRED PCB HOLE CONSTRUCTION		METRIC (mm)
DRILL (USE Ø 1.6 METRIC DRILL)		Ø 1.600 ± 0.025
COPPER THICKNESS		0.050 ± 0.025
PLATED-THROUGH HOLE (PTH) DIAMETER		Ø 1.50 +0.04 / -0.05

COMPATIBLE PCB HOLE PLATING OPTIONS:
 • IMMERSION TIN
 • IMMERSION SILVER
 • ELECTROLESS NICKEL IMMERSION GOLD (ENIG)
 • ORGANIC SOLDERABILITY PRESERVATIVE (OSP)

APPLICABLE FOR NOMINAL PCB THICKNESS 1.5mm OR THICKER
 CONSULT PRODUCT ENGINEERING FOR OTHER PCB THICKNESS PLATING, AND CONSTRUCTION



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM FUNDAMENTAL TOLERANCING PRINCIPLE ISO 8015 FOR MISSING DIMENSIONS REFER TO 3D MODEL	
GENERAL TOLERANCE: -	
MATERIAL: CuNiSi R580 (C19010 R580)	
WEIGHT: -	THIRD ANGLE PROJECTION
SURFACE FINISH: IndiCoat	
DRAWN	NAME
CHECKED	DATE
APPROVED	SEE REVISION TABLE

ENNOVI™	
THIS DRAWING CONTAINS INFORMATION THAT IS THE PROPERTY OF ENNOVI™ AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
TITLE: 0.8 EON PRESSFIT 2.8MM BLADE	SCALE: -
DRAWING NO.: IA6523	SIZE: A3
DESCRIPTION: -	SHEET 1 / 1

NOTES (UNLESS OTHERWISE SPECIFIED):

- MATERIAL:**
 - COPPER ALLOY; SEE CHART FOR OPTIONS
- EYE FINISH:**
 - POST-PLATED PER DRAWING E-MLG03034-FIN
- PCB HOLE REQUIREMENTS:**
 - SEE REQUIRED PCB HOLE CONSTRUCTION CHART

4. MAX TEMP. RATING IS TEMPERATURE AT WHICH MATERIAL BEGINS TO STRESS RELAX. THE PCB GLASS TRANSITION TEMPERATURE RATING (T_g) MUST ALSO BE 20°C HIGHER THAN MAX APPLICATION TEMPERATURE FOR PROPER INTERFACE PERFORMANCE.

- DIMENSIONS AND GEOMETRIES SHOWN ARE SYMBOLIC REPRESENTATIONS ONLY.
- CONSULT PRODUCT ENGINEERING FOR POSSIBLE DIMENSIONAL CHANGES.

AVAILABLE ALLOYS		
TYPE	% IACS	MAX TEMP. RATING Δ
PHOSPHOR BRONZE	13-20	125°C
HIGH PERFORMANCE ALLOY	50	175°C
HIGH CONDUCTIVITY ALLOY	75-80	200°C

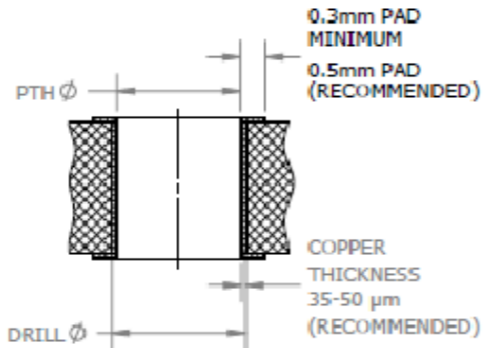
REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	9/14/2007	RLS
B	ADDED PCB HOLE CONSTRUCTION SKETCH	4/6/2009	JDP
C	UPDATED AVAILABLE ALLOYS CHART	10/16/2009	JDP
D	UPDATED DRAWING VIEWS AND NOTES	12/05/2013	JDP
E	UPD. HOLE CONSTRUCT CHART, ALLOY CHART, ADD TOL.	06/21/2014	YF
F	UPD. HOLE CONSTRUCT CHART, DIM.	4/18/2016	YF
G	UPD. DIM SCHEME, ADD NOTES #5 & #6, UPD. VIEWS & NOTES	10/30/2020	YF

REQUIRED PCB HOLE CONSTRUCTION		METRIC (mm)
DRILL (USE ϕ 1.6 METRIC DRILL)		ϕ 1.600 \pm 0.025
COPPER THICKNESS		0.050 \pm 0.025
PLATED-THROUGH HOLE (PTH) DIAMETER		ϕ 1.50 $\begin{matrix} +0.04 \\ -0.05 \end{matrix}$

COMPATIBLE PCB HOLE PLATING OPTIONS:

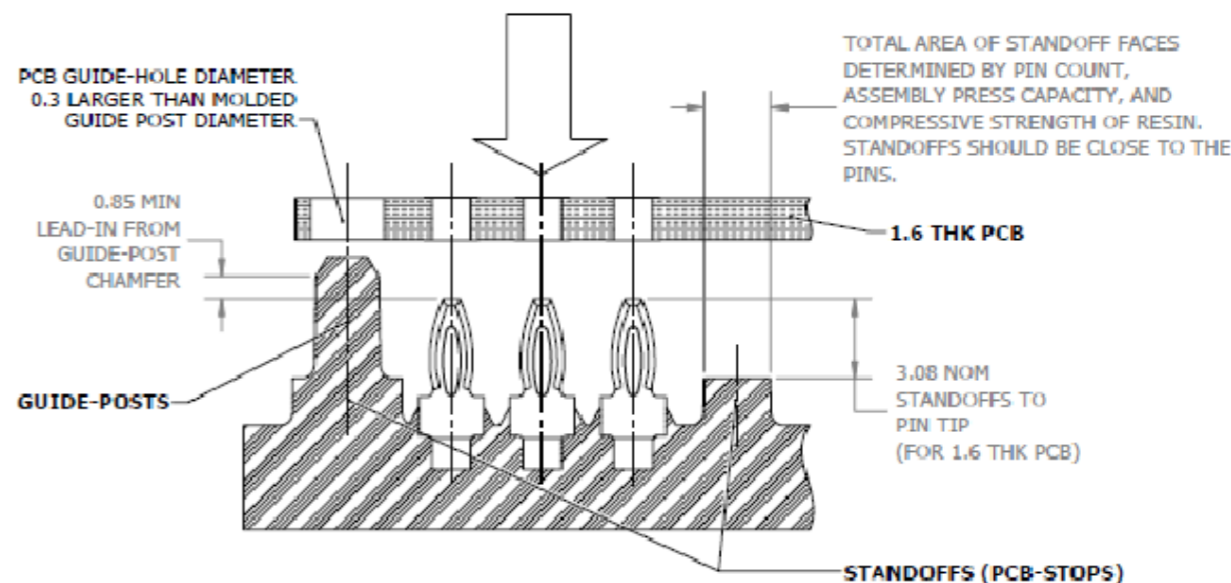
- IMMERSION TIN
- IMMERSION SILVER
- ELECTROLESS NICKEL IMMERSION GOLD (ENIG)
- ORGANIC SOLDERABILITY PRESERVATIVE (OSP)

APPLICABLE FOR NOMINAL PCB THICKNESS 1.5mm OR THICKER
CONSULT PRODUCT ENGINEERING FOR OTHER PCB THICKNESS PLATING, AND CONSTRUCTION

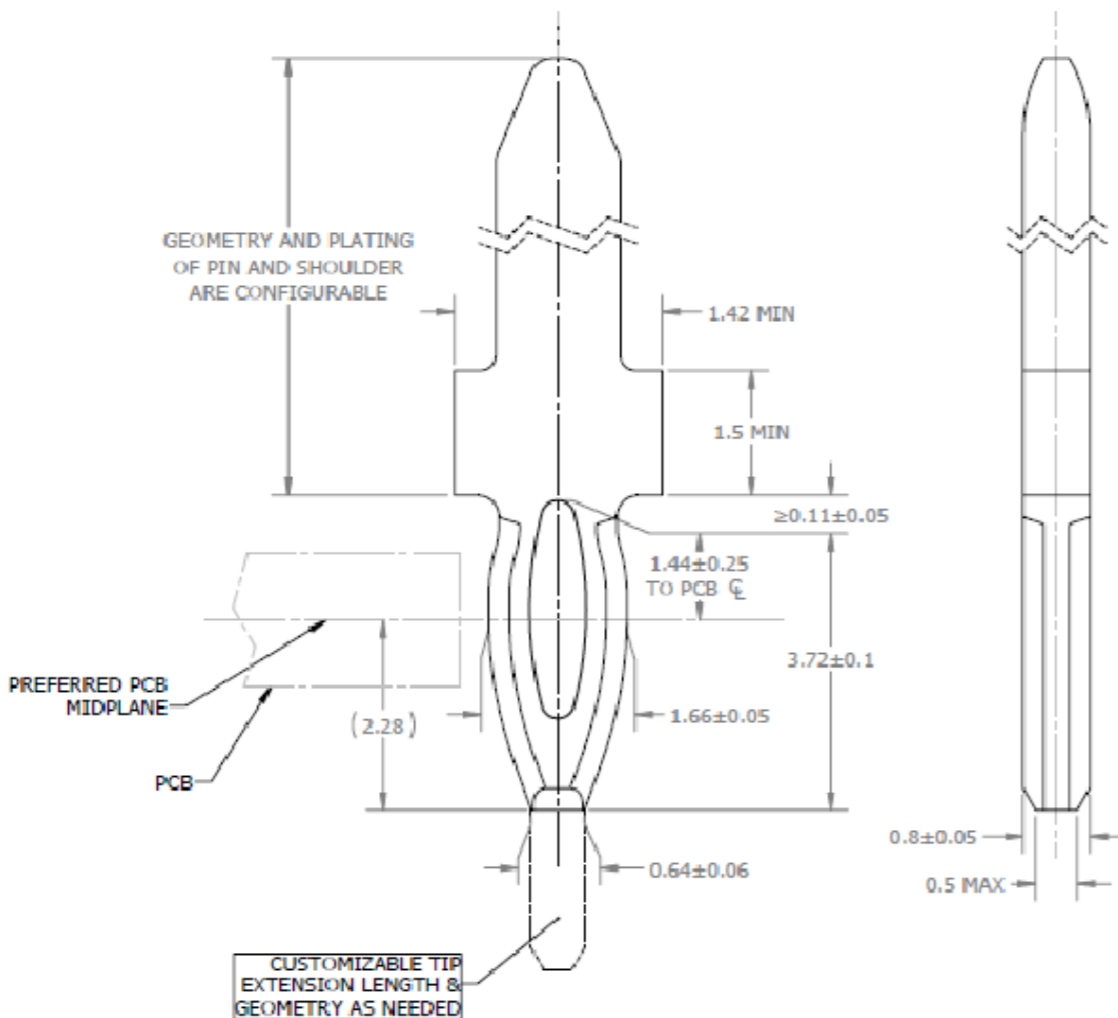
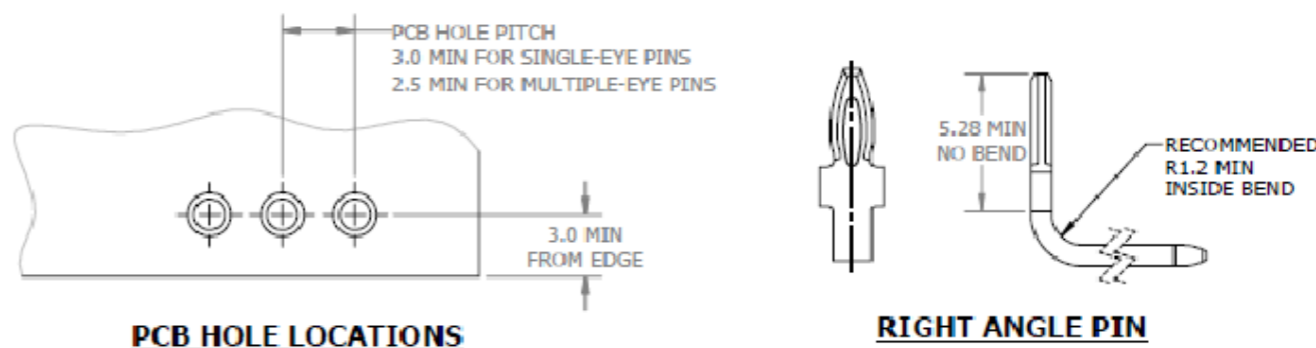


SUGGESTED APPLICATION DESIGN PRACTICES


THE PUSH TOOL USED TO PRESS THE PCB ONTO THE PINS SHOULD ENGAGE ONLY THE BOARD LAMINATE (NOT TRACES) AND ENGAGE CLOSE TO THE PINS AS WELL AS DIRECTLY OVER EACH STANDOFF SURFACE.



OVERMOLDED HOUSING WITH PRESS-FITS



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UNITS: mm		DRAWN: Y. RUKUDA 1458/2007		DATE: 1458/2007			
P/N: 080_EON_150		CHECKED: G. YORIGIAN 1458/2007		TITLE: 0.8 EON PRESS-FIT APPLICATION			
MATERIAL: SEE NOTES		SIZE: C		DWG. NO.: E-MLG03034-APP		REV: G	
FINISH: SEE NOTES		DO NOT SCALE DRAWING		SHEET 1 OF 1			